SUPPLEMENTAL AMENDMENT UNDER 37 C.F.R. § 1.116

U.S. Appln. No. 10/045,651

Attorney Docket No. O80298

REMARKS

Substance of Telephonic Interview.

Applicants wish to express appreciation to Examiner Christopher Lavin for the courtesy

of a telephonic interview held with Applicants' representative Michael Faibisch (Reg. No.

46,427) on September 25, 2006. In the interview the Examiner asserted that the invention of

claims 16 and 17 is disclosed in the Kosmowski et al. reference (US 5,529,441), particularly with

reference to Fig. 2. Applicants' representative agreed to consider the applicability of this

reference, and to amend the claims if needed. No agreement was reached regarding the

substance of an amendment

General Remarks

Claims 16 - 18 and 20 - 24 are pending in the application. Claim 25 is canceled herein

without prejudice or disclaimer. Claims 16 - 18 are currently amended with the self-explanatory

amendments shown above. Support for the proposed amendments is found at Figs. 10A, 10B

and at paragraphs [0133] - [0144] of the Patent Application Publication, inter alia. Note, for

example, that via hole alignment patterns are shown in Fig. 10B as passing though the upper

layer only, as compared to through holes 1024 which are shown as passing through several

lavers.

Applicants have carefully studied the Kosmowski et al. reference (US 5,529,441)

discussed in the telephonic interview, which shows and describes drill coordinate optimization

for multi-layered printed circuit boards. The holes (opening region 42) that are provided for

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alignment of subsequent drilling operations, pass through the upper layer and through several

layers beneath the upper layer.

Claim 16 has been amended to distinctly point out that detecting is performed on at least

two holes passing through the upper layer without passing through the lower layer located

immediately beneath the upper layer. Claim 17 has been amended to point out that the receiving

operation is performed on a multi-layered printed circuit board substrate in which at least one

hole passes through the upper layer without passing through the lower layer located immediately

beneath the upper layer. As noted above, nothing in Kosmowski et al. shows, describes or

suggests employing openings that only pass through the upper layer without passing through the

lower layer immediately beneath the upper layer.

In view of the foregoing, and arguments advanced in previous responses, Applicants

respectfully submit that claims 16 and 17 are patentable over the prior art of record, including the

Kosmowski et al. and request that the rejection of these claims be withdrawn. Claims 18, and 20

- 24 which depend directly and ultimately from claim 17 are patentable at least be virtue of their

dependency from claim 17.

In view of the foregoing, this application is believed to be in condition for allowance.

Favorable reconsideration and allowance of the application are respectfully requested.

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Applicant herewith petitions the Director of the USPTO to extend the time for reply to

the above-identified Office Action for an appropriate length of time if necessary. Unless a check

is attached, any fee due under 37 U.S.C. § 1.17(a) is being paid via the USPTO Electronic Filing

System (EFS). The USPTO is also directed and authorized to charge all required fees, except for

the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any

overpayments to said Deposit Account.

Respectfully submitted,

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WASHINGTON OFFICE CUSTOMER NUMBER

Date: September 27, 2006

/Kelly G. Hyndman 39,234/ Kelly G. Hyndman Registration No. 39,234

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